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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	52
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 20x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd21j17a-au

2. Configuration Summary

	SAM D21J	SAM D21G	SAM D21E
Pins	64	48 (45 for WLCSP)	32 (35 for WLCSP)
General Purpose I/O-pins (GPIOs)	52	38	26
Flash	256/128/64/32KB	256/128/64/32KB	256/128/64/32KB
SRAM	32/16/8/4KB	32/16/8/4KB	32/16/8/4KB
Timer Counter (TC) instances	5	3	3
Waveform output channels per TC instance	2	2	2
Timer Counter for Control (TCC) instances	3	3	3
Waveform output channels per TCC	8/4/2	8/4/2	6/4/2
DMA channels	12	12	12
USB interface	1	1	1
Serial Communication Interface (SERCOM) instances	6	6	4
Inter-IC Sound (I^2S) interface	1	1	1
Analog-to-Digital Converter (ADC) channels	20	14	10
Analog Comparators (AC)	2	2	2
Digital-to-Analog Converter (DAC) channels	1	1	1
Real-Time Counter (RTC)	Yes	Yes	Yes
RTC alarms	1	1	1
RTC compare values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values
External Interrupt lines	16	16	16
Peripheral Touch Controller (PTC) X and Y lines	16x16	12x10	10x6
Maximum CPU frequency	48MHz		

Table 3-2. Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E15B-AU	32K	4K	TQFP32	Tray
ATSAMD21E15B-AUT				Tape & Reel
ATSAMD21E15B-AF				Tray
ATSAMD21E15B-AFT				Tape & Reel
ATSAMD21E15B-MU			QFN32	Tray
ATSAMD21E15B-MUT				Tape & Reel
ATSAMD21E15B-MF				Tray
ATSAMD21E15B-MFT				Tape & Reel
ATSAMD21E15B-UUT			WLCSP35 (GJR)	Tape & Reel
ATSAMD21E16B-AU	64K	8K	TQFP32	Tray
ATSAMD21E16B-AUT				Tape & Reel
ATSAMD21E16B-AF				Tray
ATSAMD21E16B-AFT				Tape & Reel
ATSAMD21E16B-MU			QFN32	Tray
ATSAMD21E16B-MUT				Tape & Reel
ATSAMD21E16B-MF				Tray
ATSAMD21E16B-MFT				Tape & Reel
ATSAMD21E16B-UUT	64K	8K	WLCSP35 (GJR)	Tape & Reel

Table 3-3. Device Variant C

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E15C-UUT	32K	4K	WLCSP35 (GJS)	Tape & Reel
ATSAMD21E16C-UUT	64K	8K	WLCSP35 (GJS)	Tape & Reel

3.2 SAM D21G

Table 3-4. Device Variant A

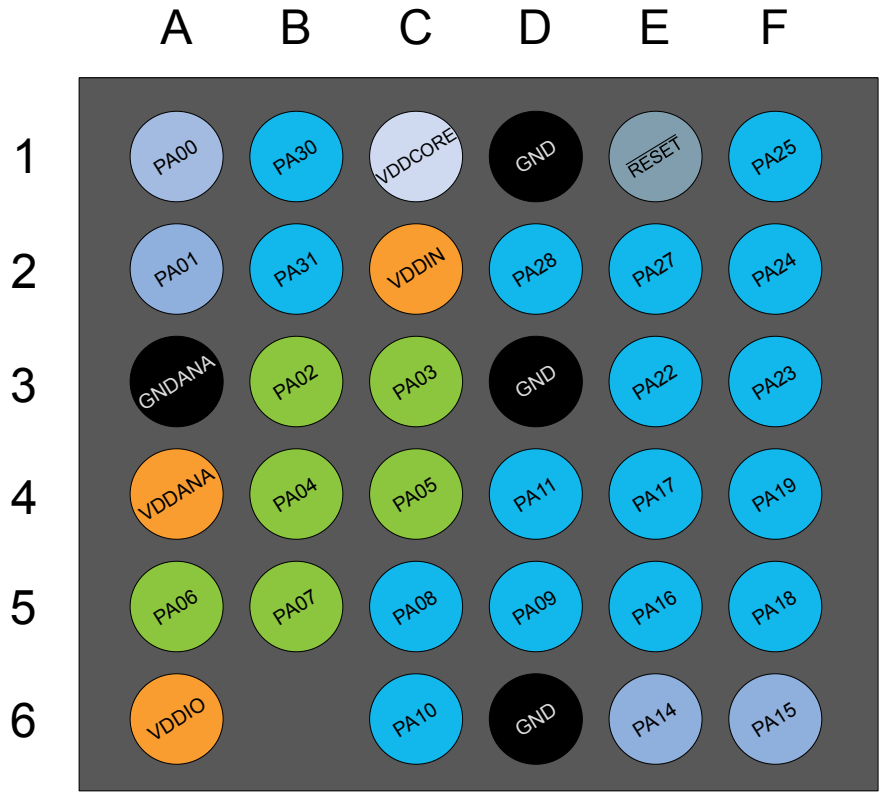
Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G15A-AU	32K	4K	TQFP48	Tray
ATSAMD21G15A-AUT				Tape & Reel
ATSAMD21G15A-AF				Tray
ATSAMD21G15A-AFT				Tape & Reel
ATSAMD21G15A-MU			QFN48	Tray
ATSAMD21G15A-MUT				Tape & Reel
ATSAMD21G15A-MF				Tray
ATSAMD21G15A-MFT				Tape & Reel
ATSAMD21G16A-AU	64K	8K	TQFP48	Tray
ATSAMD21G16A-AUT				Tape & Reel
ATSAMD21G16A-AF				Tray
ATSAMD21G16A-AFT				Tape & Reel
ATSAMD21G16A-MU			QFN48	Tray
ATSAMD21G16A-MUT				Tape & Reel
ATSAMD21G16A-MF				Tray
ATSAMD21G16A-MFT				Tape & Reel
ATSAMD21G17A-AU	128K	16K	TQFP48	Tray
ATSAMD21G17A-AUT				Tape & Reel
ATSAMD21G17A-AF				Tray
ATSAMD21G17A-AFT				Tape & Reel
ATSAMD21G17A-MU			QFN48	Tray
ATSAMD21G17A-MUT				Tape & Reel
ATSAMD21G17A-MF				Tray
ATSAMD21G17A-MFT				Tape & Reel
ATSAMD21G17A-UUT			WLCSP45	Tape & Reel

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G18A-AU	256K	32K	TQFP48	Tray
ATSAMD21G18A-AUT				Tape & Reel
ATSAMD21G18A-AF				Tray
ATSAMD21G18A-AFT				Tape & Reel
ATSAMD21G18A-MU			QFN48	Tray
ATSAMD21G18A-MUT				Tape & Reel
ATSAMD21G18A-MF				Tray
ATSAMD21G18A-MFT				Tape & Reel
ATSAMD21G18A-UUT			WLCSP45	Tape & Reel

Table 3-5. Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G15B-AU	32K	4K	TQFP48	Tray
ATSAMD21G15B-AUT				Tape & Reel
ATSAMD21G15B-AF				Tray
ATSAMD21G15B-AFT				Tape & Reel
ATSAMD21G15B-MU			QFN48	Tray
ATSAMD21G15B-MUT				Tape & Reel
ATSAMD21G15B-MF				Tray
ATSAMD21G15B-MFT				Tape & Reel
ATSAMD21G16B-AU	64K	8K	TQFP48	Tray
ATSAMD21G16B-AUT				Tape & Reel
ATSAMD21G16B-AF				Tray
ATSAMD21G16B-AFT				Tape & Reel
ATSAMD21G16B-MU			QFN48	Tray
ATSAMD21G16B-MUT				Tape & Reel
ATSAMD21G16B-MF				Tray
ATSAMD21G16B-MFT				Tape & Reel

5.3.2 WLCSP35


A B C D E F
1 2 3 4 5 6
PA00 PA30 VDDCORE GND RESET PA25
PA01 PA31 VDDIN PA28 PA27 PA24
GNDANA PA02 PA03 GND PA22 PA23
VDDANA PA04 PA05 PA11 PA17 PA19
PA06 PA07 PA08 PA09 PA16 PA18
VDDIO PA10 GND PA14 PA15
DIGITAL PIN
ANALOG PIN
OSCILLATOR
GROUND
INPUT SUPPLY
REGULATED OUTPUT SUPPLY
RESET PIN

7. Processor And Architecture

7.1 Cortex M0+ Processor

The SAM D21 implements the ARM® Cortex®-M0+ processor, based on the ARMv6 Architecture and Thumb®-2 ISA. The Cortex M0+ is 100% instruction set compatible with its predecessor, the Cortex-M0 core, and upward compatible to Cortex-M3 and M4 cores. The ARM Cortex-M0+ implemented is revision r0p1. For more information refer to http://www.arm.com.

7.1.1 Cortex M0+ Configuration

Table 7-1. Cortex M0+ Configuration

Features	Configurable option	Device configuration
Interrupts	External interrupts 0-32	28
Data endianness	Little-endian or big-endian	Little-endian
SysTick timer	Present or absent	Present
Number of watchpoint comparators	0, 1, 2	2
Number of breakpoint comparators	0, 1, 2, 3, 4	4
Halting debug support	Present or absent	Present
Multiplier	Fast or small	Fast (single cycle)
Single-cycle I/O port	Present or absent	Present
Wake-up interrupt controller	Supported or not supported	Not supported
Vector Table Offset Register	Present or absent	Present
Unprivileged/Privileged support	Present or absent	Absent(1)
Memory Protection Unit	Not present or 8-region	Not present
Reset all registers	Present or absent	Absent
Instruction fetch width	16-bit only or mostly 32-bit	32-bit

Note:

1. All software run in privileged mode only.

The ARM Cortex-M0+ core has two bus interfaces:

- Single 32-bit AMBA-3 AHB-Lite system interface that provides connections to peripherals and all system memory, which includes flash and RAM.
- Single 32-bit I/O port bus interfacing to the PORT with 1-cycle loads and stores.

7.1.2 Cortex-M0+ Peripherals

- System Control Space (SCS)
  - The processor provides debug through registers in the SCS. Refer to the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- System Timer (SysTick)

  - The System Timer is a 24-bit timer that extends the functionality of both the processor and the NVIC. Refer to the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- Nested Vectored Interrupt Controller (NVIC)
  - External interrupt signals connect to the NVIC, and the NVIC prioritizes the interrupts. Software can set the priority of each interrupt. The NVIC and the Cortex-M0+ processor core are closely coupled, providing low latency interrupt processing and efficient processing of late arriving interrupts. Refer to Nested Vector Interrupt Controller and the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- System Control Block (SCB)
  - The System Control Block provides system implementation information, and system control. This includes configuration, control, and reporting of the system exceptions. Refer to the Cortex-M0+ Devices Generic User Guide for details (www.arm.com).
- Micro Trace Buffer (MTB)
  - The CoreSight MTB-M0+ (MTB) provides a simple execution trace capability to the Cortex-M0+ processor. Refer to section Micro Trace Buffer and the CoreSight MTB-M0+ Technical Reference Manual for details (www.arm.com).

7.1.3 Cortex-M0+ Address Map

Table 7-2. Cortex-M0+ Address Map

Address	Peripheral
0xE000E000	System Control Space (SCS)
0xE000E010	System Timer (SysTick)
0xE000E100	Nested Vectored Interrupt Controller (NVIC)
0xE000ED00	System Control Block (SCB)
0x41006000 (see also Product Mapping)	Micro Trace Buffer (MTB)

7.1.4 I/O Interface

7.1.4.1 Overview

Because accesses to the AMBA® AHB-Lite™ and the single cycle I/O interface can be made concurrently, the Cortex-M0+ processor can fetch the next instructions while accessing the I/Os. This enables single cycle I/O accesses to be sustained for as long as needed. Refer to *CPU Local Bus* for more information.

7.1.4.2 Description

Direct access to PORT registers.

7.2 Nested Vector Interrupt Controller

7.2.1 Overview

The Nested Vectored Interrupt Controller (NVIC) in the SAM D21 supports 32 interrupt lines with four different priority levels. For more details, refer to the Cortex-M0+ Technical Reference Manual (www.arm.com).

7.2.2 Interrupt Line Mapping

Each of the 28 interrupt lines is connected to one peripheral instance, as shown in the table below. Each peripheral can have one or more interrupt flags, located in the peripheral's Interrupt Flag Status and Clear

The MTB has fixed QoS level 3 and the DSU has fixed QoS level 1.

The CPU QoS level can be written/read at address 0x41007110, bits [1:0]. Its reset value is 0x0.

Refer to different master QOSCTRL registers for configuring QoS for the other masters (USB, DMAC).

7.5 AHB-APB Bridge

The AHB-APB bridge is an AHB slave, providing an interface between the high-speed AHB domain and the low-power APB domain. It is used to provide access to the programmable control registers of peripherals.

AHB-APB bridge is based on AMBA APB Protocol Specification V2.0 (ref. as APB4) including:

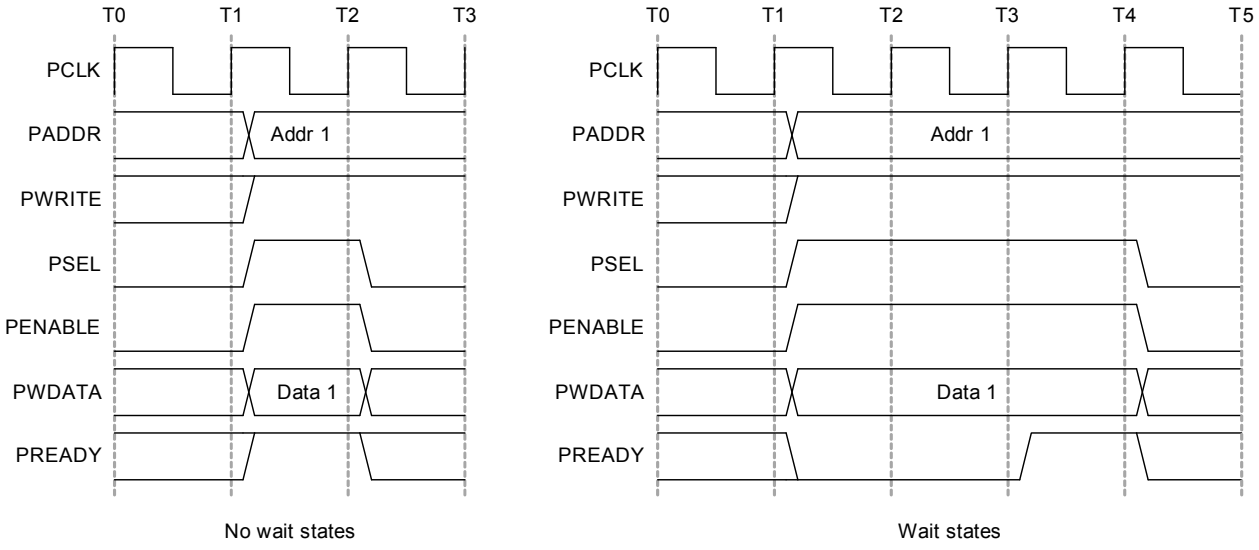
- Wait state support
- Error reporting
- Transaction protection
- Sparse data transfer (byte, half-word and word)

Additional enhancements:

- Address and data cycles merged into a single cycle
- Sparse data transfer also apply to read access

to operate the AHB-APB bridge, the clock (CLK_HPBx_AHB) must be enabled. See *PM – Power Manager* for details.

Figure 7-1. APB Write Access.



Bit	15	14	13	12	11	10	9	8
Access								
Reset								

Bit	7	6	5	4	3	2	1	0
		EIC	RTC	WDT	GCLK	SYSCTRL	PM	
Access		R/W	R/W	R/W	R/W	R/W	R/W	
Reset		0	0	0	0	0	0	

Bit 6 – EIC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 5 – RTC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 4 – WDT:
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – GCLK
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – SYSCTRL
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – PORT
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – NVMCTRL
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

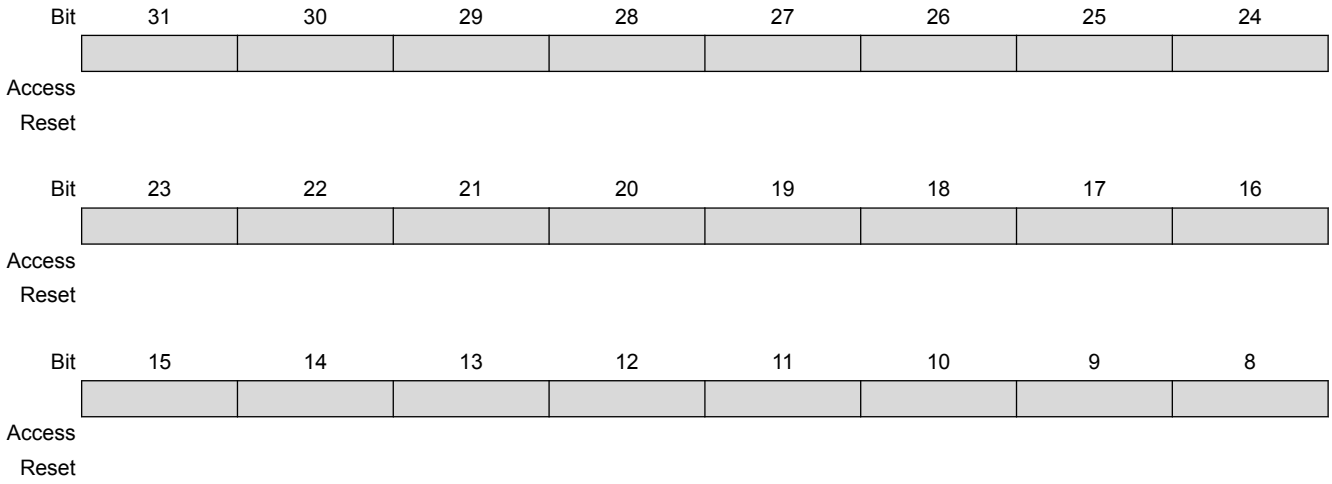
Bit 1 – DSU
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x000002
Property: –



Bit	7	6	5	4	3	2	1	0
		MTB	USB		PORT	NVMCTRL	DSU	
Access		R/W	R/W		R/W	R/W	R/W	
Reset		0	0		0	0	1	

Bit 6 – MTB
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 5 – USB
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – PORT
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – NVMCTRL
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – DSU
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

7.6.2.3 PAC2 Register Description

Write Protect Clear

Name: WPCLR
Offset: 0x00

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 16 – ADC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 11, 12, 13, 14, 15 – TC3, TC4, TC5, TC6, TC7
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 8, 9, 10 – TCCn
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 2, 3, 4, 5, 6, 7 – SERCOMn
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

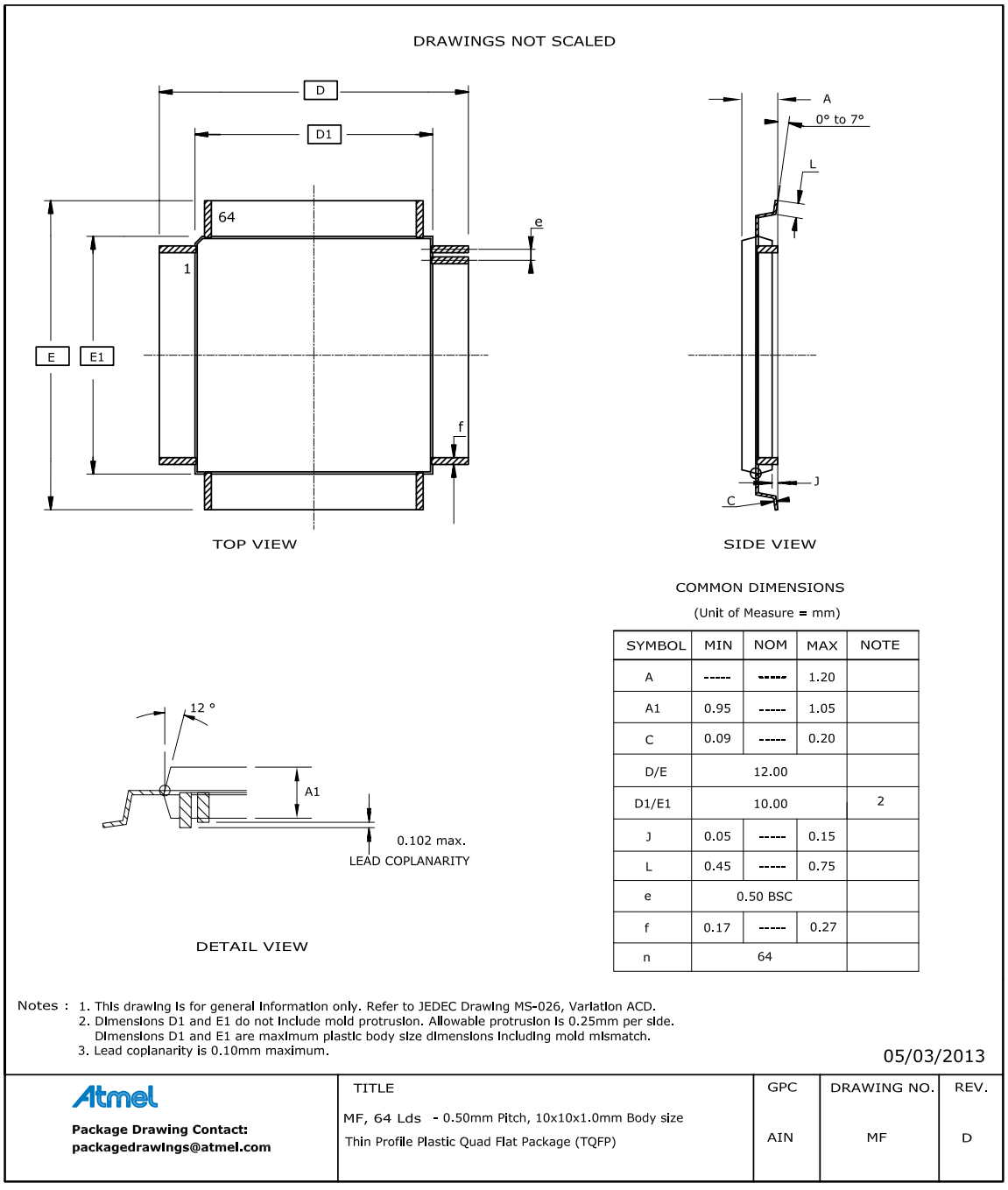
Bit 1 – EVSYS
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

8.2 Package Drawings

8.2.1 64 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		12.00		
D1/E1		10.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		64		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ACD.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

05/03/2013

	TITLE	GPC	DRAWING NO.	REV.
Atmel **Package Drawing Contact:** **packagedrawings@atmel.com**	MF, 64 Lds - 0.50mm Pitch, 10x10x1.0mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	AIN	MF	D

Table 8-2. Device and Package Maximum Weight

300	mg

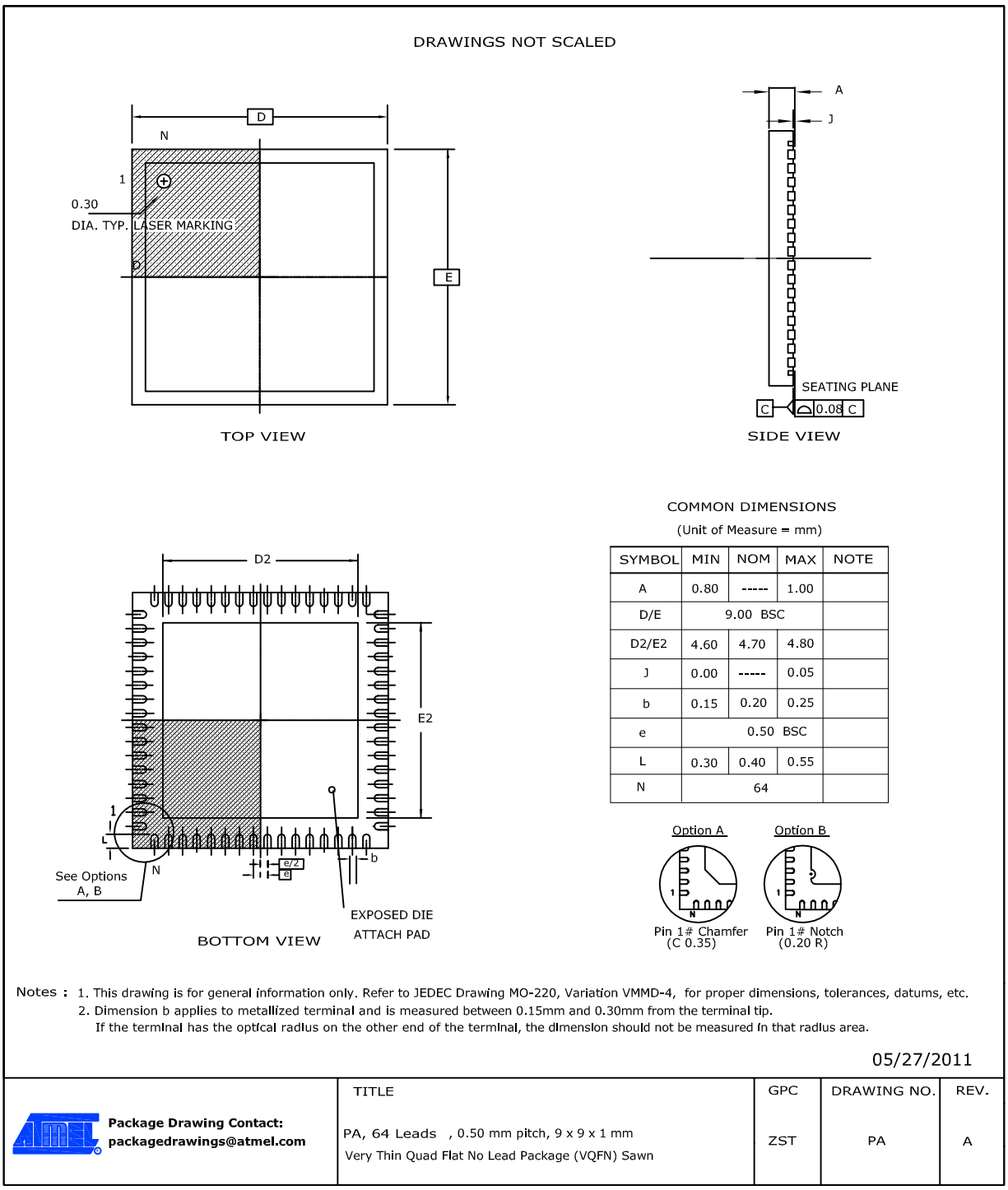
Table 8-3. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-4. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.2 64 pin QFN



Note: The exposed die attach pad is not connected electrically inside the device.

Table 8-5. Device and Package Maximum Weight

200	mg

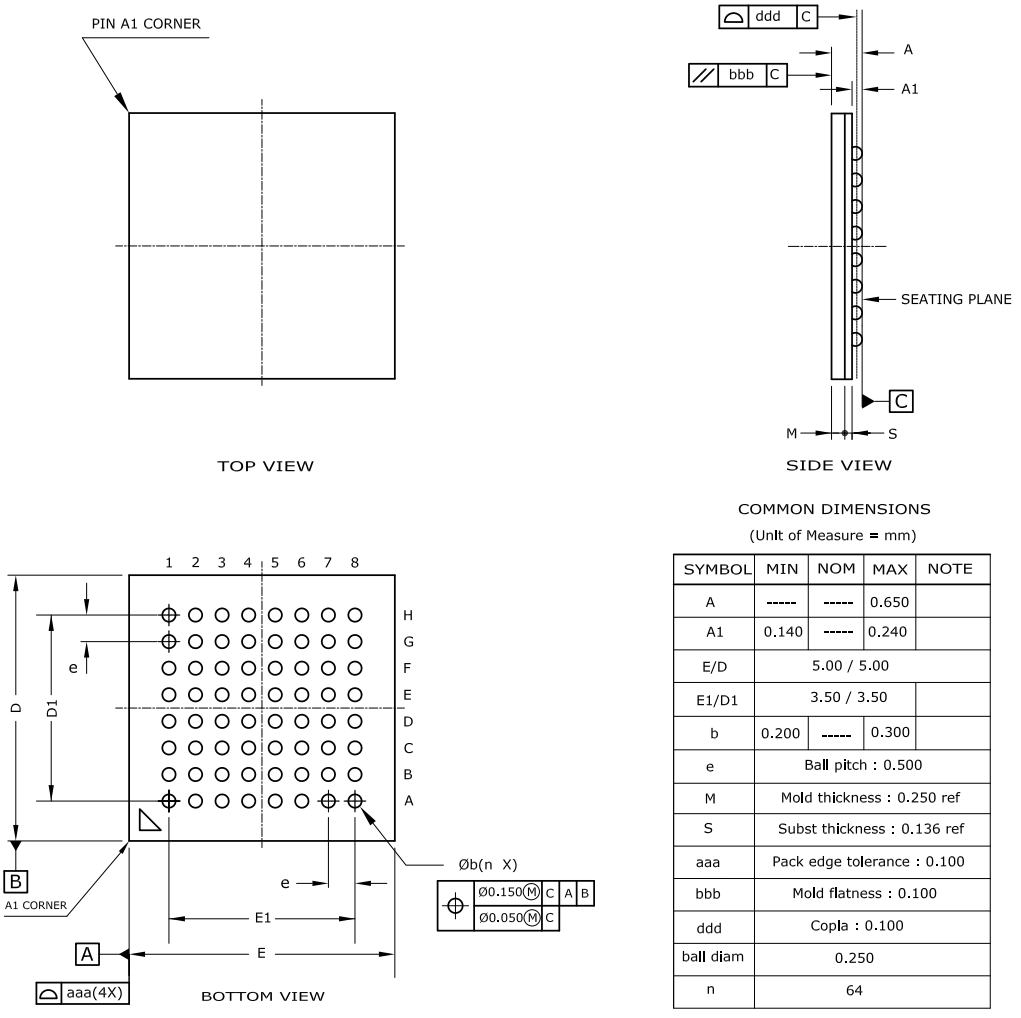
Table 8-6. Package Charateristics

Moisture Sensitivity Level	MSL3

Table 8-7. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.3 64-ball UFBGA



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	0.650	
A1	0.140	-----	0.240	
E/D	5.00 / 5.00			
E1/D1	3.50 / 3.50			
b	0.200	-----	0.300	
e	Ball pitch : 0.500			
M	Mold thickness : 0.250 ref			
S	Subst thickness : 0.136 ref			
aaa	Pack edge tolerance : 0.100			
bbb	Mold flatness : 0.100			
ddd	Copla : 0.100			
ball diam	0.250			
n	64			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-280, Variation UCCBB for proper dimensions, tolerances, datums, etc.
2. Array as seen from the bottom of the package.
3. Dimension A includes stand-off height A1, package body thickness, and lid height, but does not include attached features.
4. Dimension b is measured at the maximum ball diameter, parallel to primary datum C.

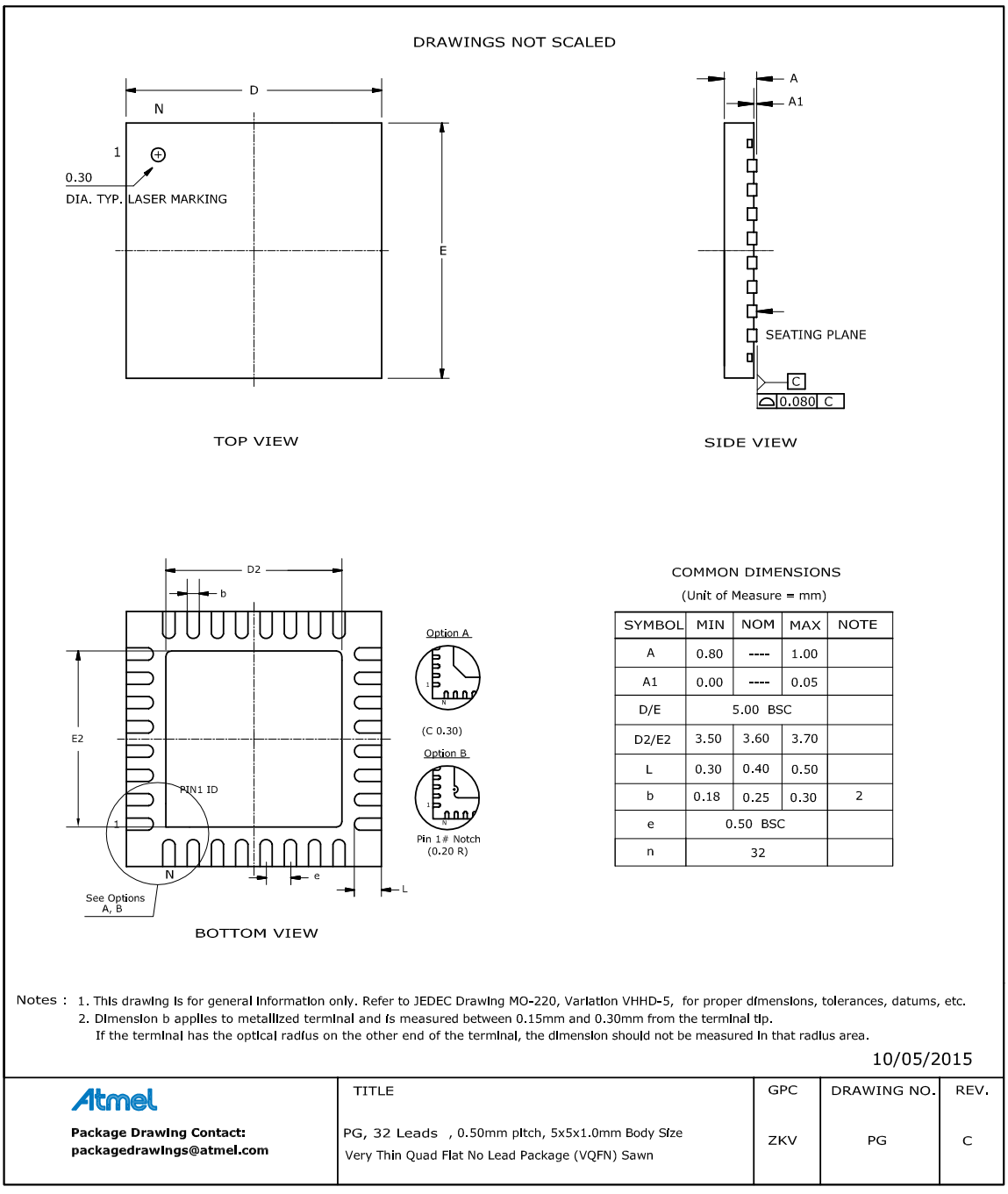
Table 8-8. Device and Package Maximum Weight

27.4	mg

Table 8-22. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.8 32 pin QFN



Note: The exposed die attach pad is connected inside the device to GND and GNDANA.

Table 8-23. Device and Package Maximum Weight

90	mg

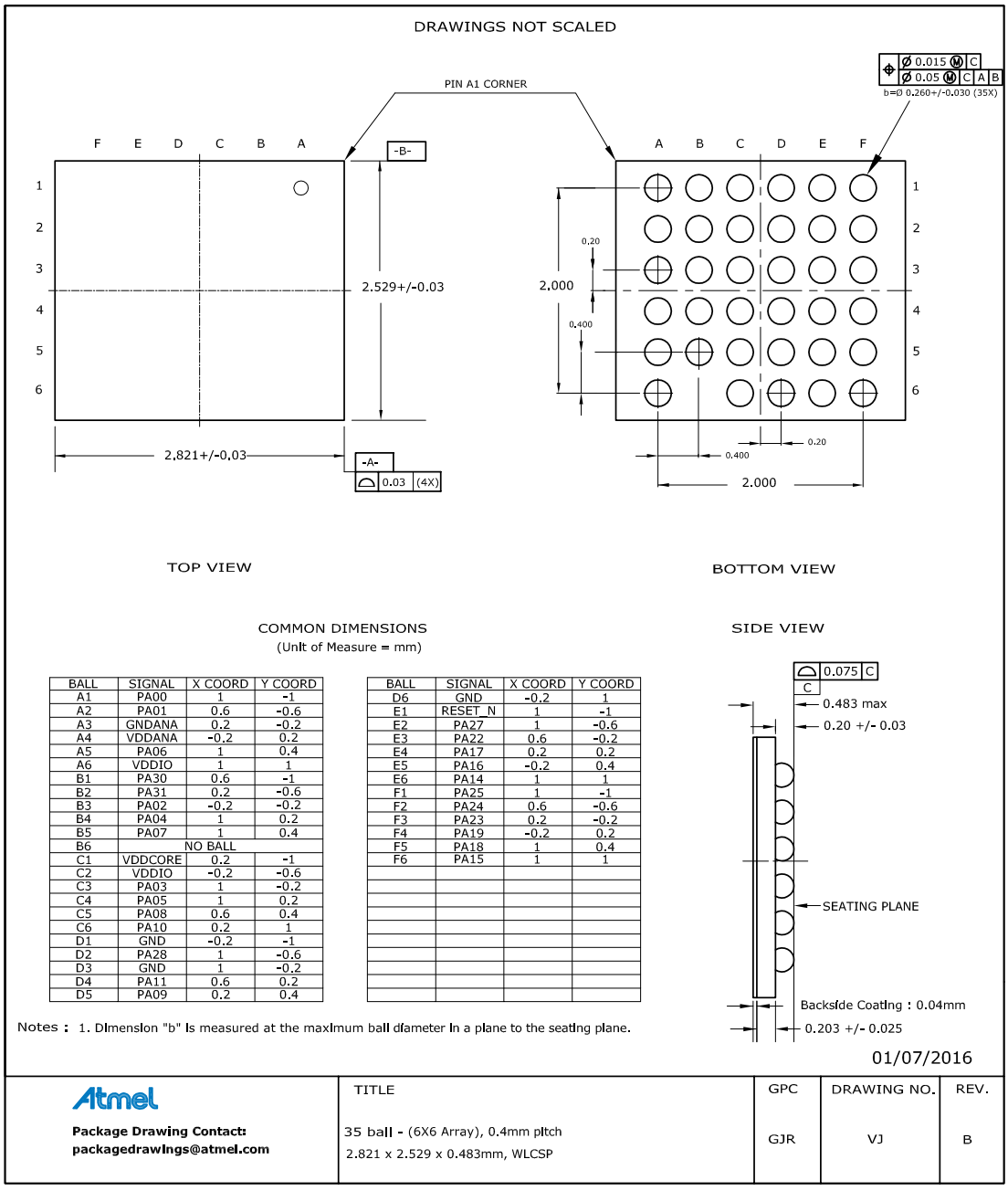
Table 8-24. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-25. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.9 35 ball WLCSP (Device Variant B)



COMMON DIMENSIONS
(Unit of Measure = mm)

BALL	SIGNAL	X COORD	Y COORD
A1	PA00	1	-1
A2	PA01	0.6	-0.6
A3	GNDANA	0.2	-0.2
A4	VDDANA	-0.2	0.2
A5	PA06	1	0.4
A6	VDDIO	1	1
B1	PA30	0.6	-1
B2	PA31	0.2	-0.6
B3	PA02	-0.2	-0.2
B4	PA04	1	0.2
B5	PA07	1	0.4
B6	NO BALL		
C1	VDDCORE	0.2	-1
C2	VDDIO	-0.2	-0.6
C3	PA03	1	-0.2
C4	PA05	1	0.2
C5	PA08	0.6	0.4
C6	PA10	0.2	1
D1	GND	-0.2	-1
D2	PA28	1	-0.6
D3	GND	1	-0.2
D4	PA11	0.6	0.2
D5	PA09	0.2	0.4

BALL	SIGNAL	X COORD	Y COORD
D6	GND	-0.2	1
E1	RESET_N	1	-1
E2	PA27	1	-0.6
E3	PA22	0.6	-0.2
E4	PA17	0.2	0.2
E5	PA16	-0.2	0.4
E6	PA14	1	1
F1	PA25	1	-1
F2	PA24	0.6	-0.6
F3	PA23	0.2	-0.2
F4	PA19	-0.2	0.2
F5	PA18	1	0.4
F6	PA15	1	1

Notes : 1. Dimension "b" is measured at the maximum ball diameter in a plane to the seating plane.

Atmel

Package Drawing Contact:
packagedrawings@atmel.com

TITLE	GPC	DRAWING NO.	REV.
35 ball - (6X6 Array), 0.4mm pitch 2.821 x 2.529 x 0.483mm, WLCSP	GJR	VJ	B

Table 8-26. Device and Package Maximum Weight

6.2	mg

Table 8-29. Device and Package Maximum Weight

6.22	mg

Table 8-30. Package Characteristics

Moisture Sensitivity Level	MSL1

Table 8-31. Package Reference

JEDEC Drawing Reference	N/A
JESD97 Classification	e1

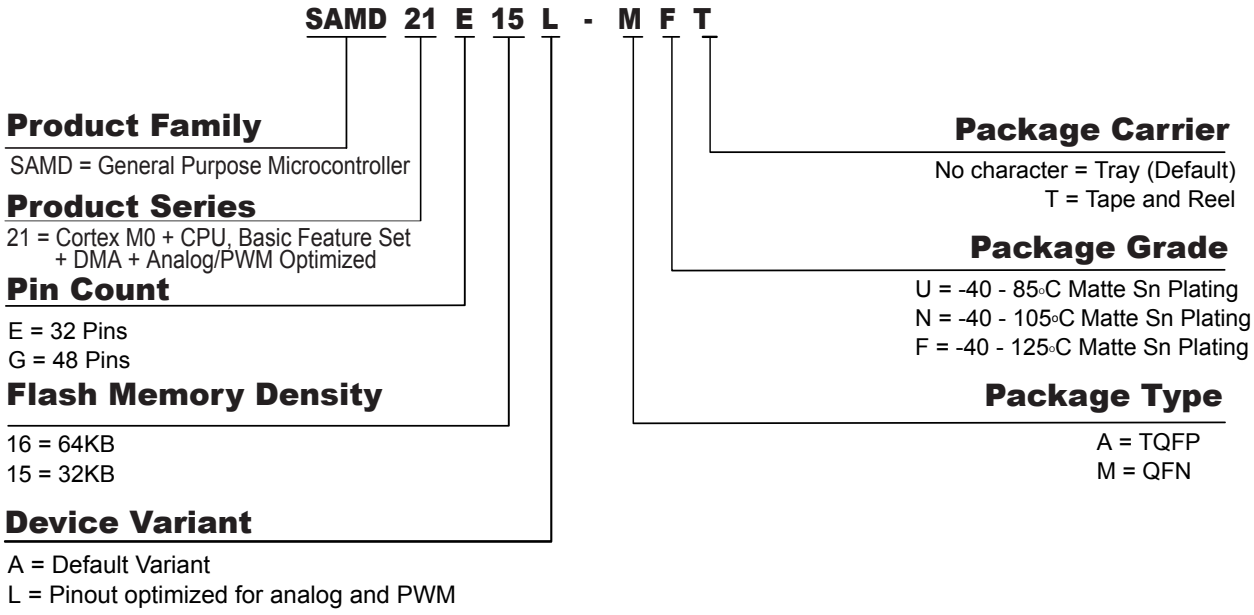
8.3 Soldering Profile

The following table gives the recommended soldering profile from J-STD-20.

Table 8-32.

Profile Feature	Green Package
Average Ramp-up Rate (217°C to peak)	3°C/s max.
Preheat Temperature 175°C ±25°C	150-200°C
Time Maintained Above 217°C	60-150s
Time within 5°C of Actual Peak Temperature	30s
Peak Temperature Range	260°C
Ramp-down Rate	6°C/s max.
Time 25°C to Peak Temperature	8 minutes max.

A maximum of three reflow passes is allowed per component.



Note:

1. Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.
2. Small form-factor packaging options may be available. Please check http://www.microchip.com/packaging for small-form factor package availability, or contact your local Sales Office.

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Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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